

ABSTRACT

A transparent adhesive composition including an epoxy resin (A), an epoxy resin-curing agent (B), and a phenoxy resin (C), wherein the epoxy resin-

5 curing agent (B) satisfies the following (1) and (2):

(1) the epoxy resin-curing agent (B) is in a powdery form and has a particle diameter (d90) at 90% cumulative distribution frequency of 2.0 μm or less; and

(2) the epoxy resin-curing agent (B) has solubility in 100 g of methyl ethyl
10 ketone at 25°C of 0.1 g or less;

a film-shaped transparent adhesive processed therefrom;

a method of producing a transparent adhesive cured layer-attached member by using the film-shaped transparent adhesive;

a method of producing an electronic component; and

15 an electronic component.

(No Suitable Figure)